#### **DESCRIPTION**

The AM06P04 is available in SOP-8 Package.

BVDSS	RDSON	ID
-40V	26 mΩ	-6.3A

#### **FEATURES**

- -40V, -6.3A
- RDS(ON) Typ =  $26m\Omega$  @ VGS = -10V
- RDS(ON) Typ =  $37m\Omega$  @ VGS = -4.5V
- Advanced Trench Technology
- Excellent RDS(ON) and Low Gate Charge

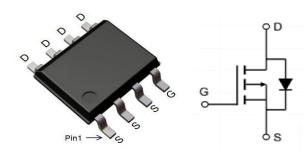
#### **APPLICATION**

- Load Switch
- PWM Application
- Power Management

### ORDERING INFORMATION

Package Type	Part Number		
SOP8	M8	AM06P04M8VR	
SPQ: 4,000/Reel	IVIO	AMUOPU4M8VR	
Note	V: Halogen free Package		
Note	R: Tape & Reel		
AiT provides all RoHS products			

## PIN DESCRIPTION



Pin#	Symbol	Function
1,2,3	S	Source
4	G	Gate
5,6,7,8	D	Drain

#### **ABSOLUTE MAXIMUM RATINGS**

T<sub>-1</sub> = 25°C unless otherwise specified

1) 20 0 diliess offici wise specifica		
V <sub>DS</sub> , Drain-to-Source Voltage		-40V
V <sub>GS</sub> , Gate-to-Source Voltage		±20V
L. Continuous Prain Current	T <sub>A</sub> = 25°C	-6.3A
I <sub>D</sub> , Continuous Drain Current	T <sub>A</sub> = 100°C	-3.78A
I <sub>DM</sub> , Pulsed Drain Current (1)		-25.2A
E <sub>AS</sub> , Single Pulse Avalanche Energy (2)		30mJ
P <sub>D</sub> , Power Dissipation	T <sub>A</sub> = 25°C	2.3W
Reuc, Thermal Resistance, Junction to Case		55°C/W
T <sub>J</sub> , T <sub>STG</sub> , Junction & Storage Temperature Range		-55°C ∼ +150°C

Stresses above may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

- (1) Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
- (2) E<sub>AS</sub> condition Starting T<sub>J</sub>=25°C, V<sub>DD</sub>=-20V, V<sub>G</sub>=-10V, R<sub>G</sub>=25 $\Omega$ , L=0.5mH, I<sub>AS</sub>=-11A

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## **ELECTRICAL CHARACTERISTICS**

Parameter	Symbol	Conditions	Min	Тур.	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	V <sub>(BV)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	-40	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 200V, V <sub>GS</sub> =0V	-	-	-1	μΑ
Gate-Body Leakage Current	Igss	V <sub>GS</sub> =±20V, V <sub>DS</sub> = 0V	-	-	±100	nA
On Characteristics		1		<u> </u>		I
Gate Threshold Voltage	V <sub>GS (th)</sub>	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250μA	-1.1	-1.6	-2.2	V
Static Drain Source ON- Resistance (3)	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> = -5A	-	26	34	mΩ
Static Drain Source ON- Resistance (3)	Rds(on)	V <sub>GS</sub> =-4.5V, I <sub>D</sub> = -3A		37	48	mΩ
Dynamic Characteristics		1		l .		I
Input Capacitance	Ciss	.,	-	887	-	pF
Output Capacitance	Coss	V <sub>DS</sub> = -20V, V <sub>GS</sub> =0V, f=1MHz	-	92	-	
Reverse Transfer Capacitance	Crss		-	79	-	
Total Gate Charge	Qg	., ., ., .,	-	35	-	nC
Gate Source Charge	Qgs	V <sub>GS</sub> =0 to -10V,	-	35	-	
Gate-Drain Charge	$Q_{gd}$	V <sub>DS</sub> =-20V, I <sub>D</sub> =-3A	-	7	-	
Switching Characteristics						
Turn-On Delay Time	t <sub>d(on)</sub>		-	13	-	
Turn-On Rese Time	tr	$V_{GS}$ =-10V, $V_{DD}$ =-20V $R_{GEN}$ =3 $\Omega$ , $I_{D}$ =-5A	-	10	-	
Turn-Off Delay Time	t <sub>d(off)</sub>		-	20	-	ns
Turn-Off Fall Time	t <sub>f</sub>		-	12	-	
Drain-Source Diode Characteristi	cs and Max	Ratings				
Maximum Continuous Drain to Source Diode Forward Current	Is	-	-	-	-6.3	Α
Maximum Pulsed Drain to Source Diode Forward Current	I <sub>SM</sub>	-	-	-	-25.2	А
Drain to Source Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =-5A	-	-	-1.2	V
Body Diode Reverse Recovery Time	Trr	I <sub>F</sub> =-3A,	-	23	-	nS
Body Diode Reverse Recovery Charge	Qrr	di/dt =100A/us	-	15	-	nC

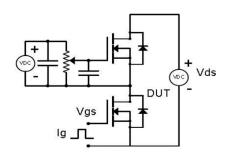
<sup>(3)</sup> R<sub>BJA</sub> is measured with the device mounted on a 1inch2 pad of 2oz copper FR4 PCB

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<sup>(4)</sup> Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%.

# TEST CIRCUIT

Fig 1. Gate Charge Test Circuit & Waveform



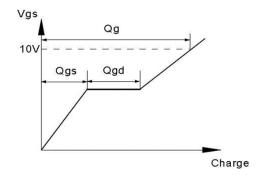
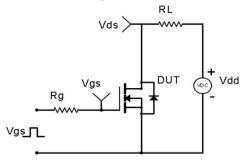


Fig 2. Resistive Switching Test Circuit & Waveform



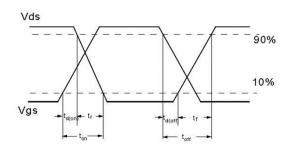
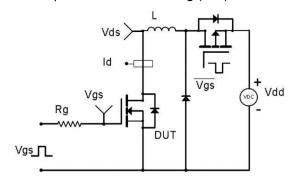


Fig 3. Unclamped Inductive Switching (UIS) Test Circuit & Waveform



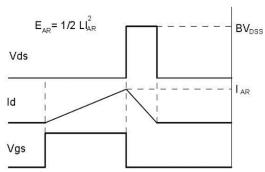
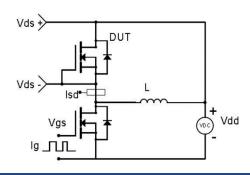
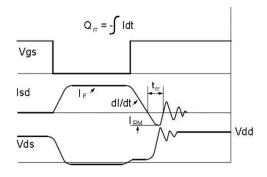


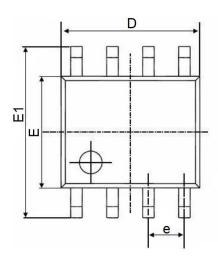
Fig 4. Diode Recovery Test Circuit & Waveform

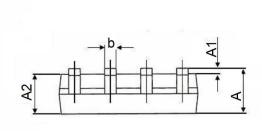


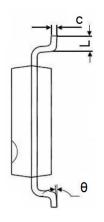


## **PACKAGE INFORMATION**

Dimension in SOP-8 (Unit: mm







Course a l	Millimeters		
Symbol	Min.	Max.	
Α	1.350	1.750	
A1	0.100	0.250	
A2	1.350	1.550	
b	0.330	0.510	
С	0.170	0.250	
D	4.700	5.100	
E	3.800	4.000	
E1	5.800	6.200	
е	1.270 BSC		
L	0.400	1.270	
θ	0°	8°	

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AM06P04 MOSFET -40V -6.3A P-CHANNEL MOSFET

## **IMPORTANT NOTICE**

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